Regarding the change of names mentioned in the document, such as Mitsubishi Electric and Mitsubishi XX, to Renesas Technology Corp.

The semiconductor operations of Hitachi and Mitsubishi Electric were transferred to Renesas Technology Corporation on April 1st 2003. These operations include microcomputer, logic, analog and discrete devices, and memory chips other than DRAMs (flash memory, SRAMs etc.) Accordingly, although Mitsubishi Electric, Mitsubishi Electric Corporation, Mitsubishi Semiconductors, and other Mitsubishi brand names are mentioned in the document, these names have in fact all been changed to Renesas Technology Corp. Thank you for your understanding. Except for our corporate trademark, logo and corporate statement, no changes whatsoever have been made to the contents of the document, and these changes do not constitute any alteration to the contents of the document itself.

Note: Mitsubishi Electric will continue the business operations of high frequency & optical devices and power devices.

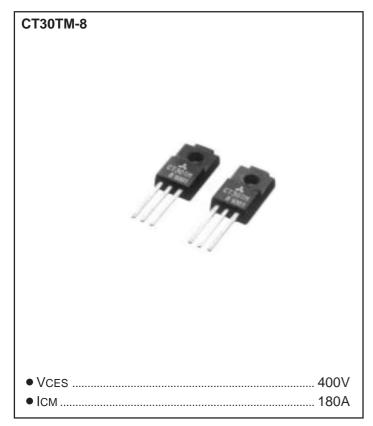
Renesas Technology Corp. Customer Support Dept. April 1, 2003

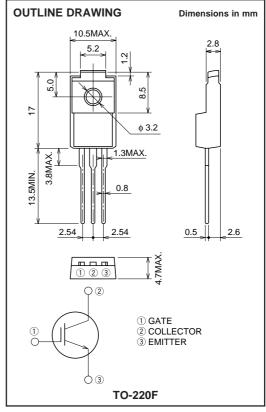


MITSUBISHI INSULATED GATE BIPOLAR TRANSISTOR

CT30TM-8

STROBE FLASHER USE





APPLICATION

Strobe Flasher.

MAXIMUM RATINGS (Tc = 25°C)

Symbol	Parameter	Conditions	Ratings	Unit
VCES	Collector-emitter voltage	VGE = 0V	400	V
VGES	Gate-emitter voltage	VCE = 0V, See notice 4	±30	V
VGEM	Peak gate-emitter voltage	VCE = 0V, tw = 0.5s	±40	V
Ісм	Collector current (Pulsed)	See figure 1	180	А
Tj	Junction temperature		-40 ~ +150	°C
Tstg	Storage temperature		-40 ~ +150	°C

ELECTRICAL CHARACTERISTICS (Tj = 25°C)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Тур.	Max.	Offic
V(BR)CES	Collector-emitter breakdown voltage	IC = 1mA, VGE = 0V	450	_	_	V
ICES	Collector-emitter leakage current	VCE = 400V, VGE = 0V	_	_	10	μΑ
IGES	Gate-emitter leakage current	$VGE = \pm 40V, VCE = 0V$	_	_	±0.1	μΑ
VGE(th)	Gate-emitter threshold voltage	VCE = 10V, IC = 1mA	_	_	7.0	V

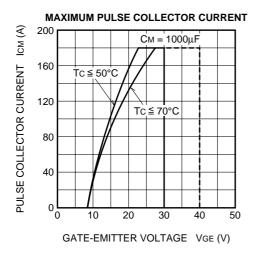
Feb.1999



CT30TM-8

STROBE FLASHER USE

PERFORMANCE CURVES

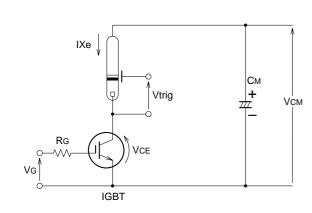


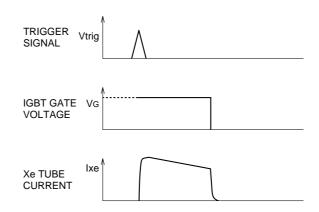
MAXIMUM PULSE COLLECTOR CURRENT 2000 MAIN CAPACITOR CM (µF) 1600 1200 800 VCM = 350V Tc ≦ 70°C 400 VGE ≧ 28V 0 **L** 120 180 140 160 200 220 PULSE COLLECTOR CURRENT ICP (A)

Figure 1

Figure 2

APPLICATION EXAMPLE





RECOMMEND CONDITION MAXIMUM CONDITION

 $\begin{array}{ll} \text{VCM} = 330 \text{V} & 360 \text{V} \\ \text{IP} = 160 \text{A} & 180 \text{A} \\ \text{CM} = 800 \mu \text{F} & 1000 \mu \text{F} \\ \text{VGE} = 28 \text{V} & \end{array}$

Notice 1. Gate drive voltage during on-period must be applied to satisfy the rating of maximum pulse collector current. And reverse gate current during turn-off must be kept less than 1A. (In general, it is satisfied if $Rg \ge 30\Omega$)

Notice 2. IGBT has MOS structure and its gate is insulated by thin silicon oxide. So please handle carefully not to suffer from electrostatic charge.

Notice 3. The operation life should be endured 5,000 shots under the charge current (lxe \leq 180A : full luminescence condition) of main condenser (CM=1000µF). Repetition period under full luminescence condition is over 3 seconds.

Notice 4. Total operation hours must be applied within 5,000 hours.

